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(54) Title: **SOLVENTLESS SILICONE PRESSURE SENSITIVE ADHESIVES WITH IMPROVED HIGH TEMPERATURE CO-
HESIVE STRENGTH**

(57) Abstract: This invention relates to silicone compositions suitable for forming pressure sensitive adhesives. More particularly,
the present invention relates to solventless curable PSA compositions suitable for forming pressure sensitive adhesive compositions
having improved high temperature cohesive strength while maintaining good tack and adhesive properties.